

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
10 February 2005 (10.02.2005)

PCT

(10) International Publication Number
WO 2005/013655 A2

(51) International Patent Classification⁷: **H05K 7/10**

(21) International Application Number:
PCT/US2004/023574

(22) International Filing Date: 21 July 2004 (21.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/630,583 29 July 2003 (29.07.2003) US

(71) Applicant (for all designated States except US): **INTEL CORPORATION** [US/US]; 2200 Mission College Boulevard, Santa Clara, CA 95052 (US).

(72) Inventor: **FRUTSCHY, Kristopher**; 2515 East Rockledge Road, Phoenix, AZ 85048 (US).

(74) Agent: **VINCENT, Lester, J.**; Blakely, Sokoloff, Taylor & Zafman, 12400 Wilshire Blvd., 7th Floor, Los Angeles, CA 90025 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: A SOCKET FOR A MICROELECTRONIC COMPONENT HAVING REDUCED ELECTRICAL RESISTANCE AND INDUCTANCE

(57) Abstract: A socket for a microelectronic component is provided. The socket has a base with metal power and ground layers, and further includes a plurality of electrically conductive socket members, some of which are connected in parallel to the metal power layer, others being connected in parallel to the metal ground layer, while others are insulated from both the metal power and ground layers for purposes of providing signals. Each electrically conductive socket member has a protrusion that breaks through an inner insulating layer that defines an opening into which the electrically conductive socket member is inserted. The protrusions are at different heights, so that some of the protrusions make contact with the metal power layer, while others are connected to the metal ground layer or to a dielectric core layer.



WO 2005/013655 A2